

Tputty[™] 403 SeriesGap Filler Material

Preliminary



SOFT AND LOW ABRASION GAP FILLER

Tputty[™] 403 is a single-part, silicone-based thermal gap filler that is soft and low abrasion. Tputty[™] 403 is ideal for applications where large or uneven gap tolerances are present. The soft and compliant nature of this material allows for the transfer of little to no pressure on mating parts. Tputty™ 403 provides excellent thermal performance and compliance.

FEATURES AND BENEFITS

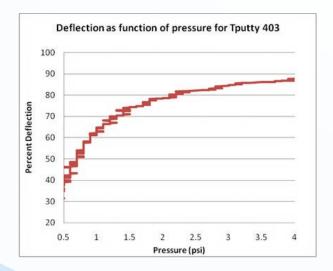
- Soft and compliant
- 2.3 W/mK thermal conductivity
- Dispensable
- Available in 75 cc, 180 cc, 360 cc and 600 cc dispensing cartridges
- Available in 20 kg pails

APPLICATIONS

- Automotive electronics
- LED Lighting
- Graphic chips
- Telecom Base Stations
- Microprocessors

PROPERTIES		TEST METHOD
Color	White	Visual
Flow Rate (75 cc taper tip, 0.125" orifice, 40 psi)	29 grams/min	Laird test method
Density	2.48 g/cc	Helium Pycnometer
Thermal Conductivity	2.3 W/mK	Hot Disk
Temperature Range	-45°C to 150°C	
Minimum Bondline thickness	0.002 in	
Deflection vs compression force (see curve)	%deflection	
Volume Resistivity	10 ¹³ Ohm-cm	ASTM D991

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.



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